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ILNAS-EN IEC 61967-1:2019

Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions

Integrierte Schaltungen - Messung von
elektromagnetischen Aussendungen -
Teil 1: Allgemeine Bedingungen und
Definitionen

Circuits intégrés - Mesure des émissions
électromagnétiques - Partie 1: Conditions
générales et définitions

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ILNAS-EN IEC 61967-1:2019

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**Integrated circuits - Measurement of electromagnetic emissions -
Part 1: General conditions and definitions
(IEC 61967-1:2018)**

Circuits intégrés - Mesure des émissions
électromagnétiques - Partie 1: Conditions générales et
définitions
(IEC 61967-1:2018)

Integrierte Schaltungen - Messung von
elektromagnetischen Aussendungen - Teil 1: Allgemeine
Bedingungen und Definitionen
(IEC 61967-1:2018)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 47A/1062/FDIS, future edition 2 of IEC 61967-1, prepared by SC 47A "Integrated circuits" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61967-1:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2019-10-16
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-01-16

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61967-2	NOTE	Harmonized as EN 61967-2
IEC 61967-4	NOTE	Harmonized as EN 61967-4
IEC 61967-5	NOTE	Harmonized as EN 61967-5
IEC 61967-6	NOTE	Harmonized as EN 61967-6
IEC 61967-8	NOTE	Harmonized as EN 61967-8
IEC 62132-1	NOTE	Harmonized as EN 62132-1
CISPR 25:2008	NOTE	Harmonized as EN 55025:2008 (not modified)

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
CISPR 16-1-1	-	Specification for radio disturbance and immunity measuring apparatus and Methods - Part 1-1: Radio disturbance and immunity measuring apparatus - Measuring apparatus	EN 55016-1-1	-



INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Integrated circuits – Measurement of electromagnetic emissions –
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**Circuits intégrés – Mesure des émissions électromagnétiques –
Partie 1: Conditions générales et définitions**

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